Overview

HP EliteBook x360 830 G6 Notebook PC



- I. HD and IR Camera (Optional)
- 2. IR camera LEDs (Optional)
- 3. Internal microphones
- 4. Camera Shutter
- 5. HD Camera LED
- 6. Ambient light sensor (Optional)

Left

- 7. Glass Clickpad
- 8. Smartcard reader (Optional)
- 9. Volume Up/Down
- 10. Vents
- 11. Power Button
- 12. USB 3.2 Gen 1 charging port



Overview



Right

- 1. Power connector
- 2. USB 3.2 Gen 1
- 3. HDMI port (Cable not included)
- 4. USB Type-C™ with Thunderbolt™
- 5. USB Type-C™ with Thunderbolt™

- 6. Audio Combo Jack
- 7. Nano Security Lock Slot (Lock sold separately)
- 8. SIM card tray¹
- 9. Touch fingerprint sensor (Optional)

1. All units have a SIM card stray but units that do not support WWAN are shipped with a non-removable SIM slot plug



Overview

At a Glance

- Eye catching, Aluminum x360 design with four usage modes that is 0.66 inches (1.69 cm) thin and with a starting weight of 2.97 lbs. (1.35 Kg)
- Choice of 8th Generation Intel® Core™ i3, i5, i7 Processors
- Optional ultrabright, ant-glare touch displays with ambient light sensor
- Choice of displays:
 - 33.8 cm (13.3") diagonal FHD IPS LED-backlit BrightView touch with Corning® Gorilla® Glass 5, 250 nits, 45% NTSC
 - 33.8 cm (13.3") diagonal FHD IPS LED-backlit BrightView touch with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC
 - 33.8 cm (13.3") diagonal FHD IPS LED-backlit Anti-Glare glass touch with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC
 - 33.8 cm (13.3") diagonal FHD IPS LED-backlit BrightView touch with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with HP Sure View*
 - 33.8 cm (13.3") diagonal FHD IPS LED-backlit Anti-Glare glass touch with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with HP Sure View*
- Enterprise grade security with HP Sure Sense, HP SureStart Gen5, HP Privacy Camera, HP Sure View Gen3¹, HP Sure Run Gen2, HP Sure Recover Gen2², HP Sure Click, SmartCard Reader² and Touch Fingerprint reader²
- New optional HP Rechargeable Active Pen²
- Ultimate connectivity with optional Wi-Fi 6², CAT16 4G/LTE WWAN, and Thunderbolt™ Docking (Dock sold separately)
- Preinstalled with Windows 10 versions or FreeDOS 3.0
- Choice of solid state drives up to 2 TB and DDR4 memory up to 32 GB
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles³
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke
- Innovative world-facing third mic improves inbound ambient noise cancellation
- Battery life up to 21 hours⁵
- Passed MIL-STD 810G testing, plus an additional 120,000 hours of reliability testing through HP's Total Test Process⁴
- Instant on/instant off with Modern Connected Standby
- 1. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- 2. Sold separately or as an optional feature
- 3. Recharges your battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
- 4. MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.
- 5. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will

naturally decrease with time and usage. See http://www.bapco.com for additional details.

*Touch-enabled display and Sure View privacy panel will lower actual brightness.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Technical Specifications

PRODUCT NAME

HP EliteBook x360 830 G6 Notebook PC

OPERATING SYSTEMS

Preinstalled Windows 10 Pro 64¹

Windows 10 Pro 64 (National Academic Only)²

Windows 10 Home 64¹

Windows 10 Home Single Language 641

FreeDOS 3.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS

Intel® Core™ i3-8145U with Intel® UHD Graphics 620 (2.1 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores)^{3,4,5,6}

Intel® Core™ i5-8265U with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6}

Intel® Core™ i5-8365U vPro™ processor with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores) ^{3,4,5,6}

Intel® Core™ i7-8565U with Intel® UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel® Core™ i7-8665U vPro™ processor with Intel® UHD Graphics 620 (1.9 GHz base frequency, up to 4.8 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) ^{3,4,5,6}

Processor Family

8th Generation Intel® Core™ i7 processor (i3-8145U)6

8th Generation Intel® Core™ i7 processor (i7-8665U and i7-8565U)⁶
8th Generation Intel® Core™ i5 processor (i5-8365U and i5-8265U)⁶

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.
- 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.



Technical Specifications

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® UHD Graphics 6207

Supports

Support HD decode, DX12, HDMI 1.4b8, HDCP 2.2

- 7. HD content required to view HD images.
- 8. HDMI cable sold separately.

DISPLAY

Touch

33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 250 nits, 45% NTSC with HD camera (1920 x 1080)^{7,9,10}

33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 250 nits, 45% NTSC with HD camera for WWAN (1920 x 1080)^{7,9,10}

33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC with Ambient Light Sensor and HD IR camera (1920 x 1080)^{7,9,10}

33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC with Ambient Light Sensor and HD IR camera for WWAN (1920 x 1080)^{7,9,10}

33.8 cm (13.3") diagonal FHD IPS Anti-Glare LED-backlit touch screen with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC with Ambient Light Sensor and HD IR camera for WWAN (1920 x 1080)^{7,9,10}

HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with Ambient Light Sensor and HD IR webcam (1920 x 1080)^{7,9,10,11*} HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS BrightView LED-backlit touch screen with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with Ambient Light Sensor and HD IR webcam for WWAN (1920 x 1080)^{7,9,10,11*}

HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS Anti-Glare LED-backlit touch screen with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with Ambient Light Sensor and HD IR webcam for WWAN (1920 x 1080)^{7,9,10,11*}

HDMI 1.4b

Supports resolution up to 4k @ 30Hz

- 7. HD content required to view HD images.
- 9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 10. Sold separately or as an optional feature.
- 11. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- *Touch-enabled display and Sure View privacy panel will lower actual brightness.



Technical Specifications

Docking station model	Total number of supported displays (Including the notebook) display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock G2	3	Dual 4K @ 60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	Dual 4k (4096 x 2160) only with: • 1 DP + TB port or • USB-C alt mode + TB port Dual 4K (3840 x 2160) with any of the DP, TB or USB-C alt mode video ports
HP Elite USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

STORAGE AND DRIVES

Primary M.2 Storage

128 GB SATA-3 SS TLC12

256 GB PCIe® NVMe™ SS Value12

256 GB PCle[®] Gen3x4 NVMe[™] SS TLC¹²

256 GB SATA-3 SED SS TLC¹²

256 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 16 GB Intel® Optane™ memory H10^{12,13,14}

512 GB PCIe® NVMe™ SS Value¹²

512 GB PCle® Gen3x4 NVMe™ SS TLC12

512 GB PCle® Gen3x4 NVMe™ SED SS TLC12

512 GB SATA-3 SS TLC (FIPS 140-2)12

512 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 32 GB Intel® Optane™ memory H10(Planned to be available Q2 2019)^{12,13,14}

1 TB PCIe® Gen3x4 NVMe™ SS TLC12

2 TB PCle® Gen3x4 NVMe™ SS TLC12

- 12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.
- 13. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.
- 14. Intel® Optane™ memory H10 only for Intel® PCIe® NVMe™ QLC M.2 SSD.



Technical Specifications

MFMORY

Maximum Memory
32 GB DDR4-2400 SDRAM¹⁵

Memory

32 GB DDR4-2400 SDRAM (2 x 16 GB)¹⁵
16 GB DDR4-2400 SDRAM (1 x 16 GB)¹⁵
16 GB DDR4-2400 SDRAM (2 x 8 GB)¹⁵
8 GB DDR4-2400 SDRAM (1 x 8 GB)¹⁵
8 GB DDR4-2400 SDRAM (2 x 4 GB)¹⁵
4 GB DDR4-2400 SDRAM (1 x 4 GB)¹⁵

Memory Slots
2 SODIMM
Both slots are upgradeable
System runs at 2400 for Intel® 8th Generation processors
Supports Dual Channel Memory

15. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel® Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, vPro $^{\text{IM}10,16}$ Intel® Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro $^{\text{IM}}$ 10,16 Intel® Wi-Fi 6 AX200 802.11a/b/g/n/ac/ax (2x2) and Bluetooth® 5 Combo, vPro $^{\text{IM}}$ 10,20 Intel® Wi-Fi 6 AX200 802.11a/b/g/n/ac/ax (2x2) Bluetooth® 5 Combo, non-vPro $^{\text{IM}}$ 10,20

WWAN

Intel® XMM™ 7262 LTE-Advanced Cat 6¹⁷
Intel® XMM™ 7360 LTE-Advanced Cat 9¹⁷
Intel® XMM™ 7560 LTE-Advanced Pro Cat 16¹⁹

NFC

NXP NPC300 Near Field Communication Module¹⁰

Miracast

Native Miracast Support¹⁸

- 10. Sold separately or as an optional feature.
- 16. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.
- 17. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 18. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 19. Gigabit class Category 16 4G LTE module is optional and must be configured at the factory. Module designed for up to 1 Gbps download speeds as carriers deploy 5 carrier aggregation and 100Mhz channel bandwidth, requires activation and separately purchased service contract. Backwards compatible to HSPA 3G technologies. Check with service provider for



Technical Specifications

coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

20. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen Integrated 3 Multi Array Microphone 2 Integrated Stereo Speakers (74 Db)

Camera

HD camera⁷

HD IR camera7

7. HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Collaboration Keyboard, backlit and spill resistant with drain

Pointing Device

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

F1 - Display Switching

F2 - Blank or Privacy

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Backlit Toggle

F10 - numlk

F11 - Wireless

F12 - Calendar

Share/Present

Call Answer

Call End

Hidden Function Keys

Fn+R - Break

Fn+S - Sys Rq



Technical Specifications

Fn+C - Scroll Lock

Fn+E - Insert

Fn+W - Pause

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen5²¹

HP Drive Lock & Automatic Drive Lock²²

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase²³

Absolute Persistence Module²⁴

Pre-boot Authentication

Software

HP Native Miracast Support²⁵

HP Connection Optimizer

HP Image Assistant

HP Hotkey Support

HP JumpStart

HP Support Assistant²⁶

HP Noise Cancellation Software

Buy Office (Sold separately)

Manageability Features

HP Driver Packs²⁷

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen3²⁸

HP Cloud Recovery²⁹

Client Security Software

HP Client Security Manager Gen530

HP Fingerprint Sensor³¹

HP Power On Authentication

Windows Defender³²

Security Management

Pre-boot Authentication

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)

SATA 0,1 port disablement (via BIOS)

Serial, USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

Support for chassis padlocks and cable lock devices

HP Sure Click³³

HP Sure Start Gen5³⁴

HP Sure Run Gen2³⁵

HP Sure Recover Gen2³⁶



Technical Specifications

HP Sure Sense³⁷

TPM

Model: Infineon SLB9670

Version: 7.85 Revision: TPM 2.0

FIPS 140-2 Compliant: Yes

Smartcard Reader

Model number: Alcor AU9560 FIPS 201 Compliant: Yes

IPv6 Compliance

Yes

MD5 Hash: Please follow the instructions below to access MD5 Hash.

Log-on to http://hp.com/support, enter your product name, select software and drivers, select OS, select driver. After selecting the driver, click on "Associated files" and then click on "Download". When opening the file, under "Purpose" you should see the appropriate "SOFTPAQ MD5:" Field Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

Yes

UEFI version: 2.6

- 21. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
- 22 HP Automatic Drive Lock is not supported on NVMe drives
- 23. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 24. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 25. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 26. HP Support Assistant requires Windows and Internet access.
- 27. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 28. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 29. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630
- 30. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.
- 31. HP Fingerprint Sensor sold separately or as an optional feature.
- 32. Windows Defender Opt in and internet connection required for updates.



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- 33. HP Sure Click is available on select HP platforms and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
- 34. HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.
- 35. HP Sure Run Gen2: See product specifications for availability.
- 36. HP Sure Recover Gen2: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.
- 37. HP Sure Sense requires Windows 10. See product specifications for availability.

POWER

Power Supply

HP Smart 45 W External AC power adapter³⁸
HP Smart 45 W External AC power adapter, 2-prong (Japan only)³⁸
HP Smart 65 W External AC power adapter³⁸
HP Smart 65 W EM External AC power adapter³⁸
HP 45 W USB Type-C™ adapter³⁸
HP 65 W USB Type-C™ adapter³⁸

Primary Battery

HP Long Life 4-cell, 53 Wh Li-ion³⁹

Battery Life

Up to 21 hours (Intel® 8th Generation CPU and 4-cell 53 WHr battery)⁴⁰

Power Cord

2-wire plug - 1 m3
3-wire plug - 1 m
3-wire plug - 1.8 m
Duckhead power cord - 1 m
Duckhead power cord - 1.8 m

- 38. Availability may vary by country.
- 39. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 40. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight
Starting weight
2.97 lbs³⁵ 1.35 kgs⁴¹

NOTE: Starting weight configuration includes FHD 400 nits BrightView Touch, 53 Wh battery, 4 GB, 128 GB SSD, HD + IR camera, No FPS, with WWAN Antenna, No NFC, and No Pen



Technical Specifications

Mainstream weight 3.13 lbs³⁵1.42 kgs⁴¹

NOTE: Mainstream weight configuration includes FHD 250 nits BrightView Touch, 53 Wh battery, 4 GB, 128 GB SSD, HD Camera, No FPS, with WWAN Antenna, No NFC and No Pen

Product Dimensions (w x d x h)
12.07 x 8.47 x 0.66 in
30.66 x 21.52 x 1.69 cm

41. Weight will vary by configuration.

PORTS/SLOTS

2 USB 3.1 Type-C™ with Thunderbolt™ support 2 USB 3.2 Gen 1 (1 Charging) 1 HDMI 1.4b⁸ 1 External Nano SIM tray (Optional)¹⁰ 1 Headphone/microphone combo 1 Smartcard reader (Optional)¹⁰ 1 AC power Nano Security Lock Slot (Lock sold separately)

Sensors
Accelerometer
Magnetometer
Gyro
ALS (ambient light sensor)
Hall Sensor

8. HDMI cable sold separately
10. Sold separately or as an optional feature.

SERVICE AND SUPPORT

HP offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc. 42

42. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications



Technical Specifications

SYSTEM UNIT

Stand-Alone Power Nominal Operating AC 19V

Requirements (AC Power) Voltage

Average Operating Power Win10
Integrated Graphics Yes

Max Operating Power UMA < 65W

Temperature Operating 32° to 95° F (0° to 35° C)

Non-operating -4° to 140° F (-20° to 60° C)

Relative Humidity Operating 10% to 90%, non-condensing

Non-operating 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock Operating 40 G, 2 ms, half-sine

Non-operating 200 G, 2 ms, half-sine

Random Vibration Operating **0.75 grms**

Non-operating 1.50 grms

Altitude (unpressurized) Operating -50 to 10,000 ft (-15.24 to 3,048 m)

Non-operating -50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard

Certifications

UL Yes
CSA Yes
FCC Compliance Yes
ENERGY STAR® Yes⁴³

EPEAT® 2019 Yes, Silver in U.S.44

ICES Yes Australia Yes NZ A-Tick Compliance Yes CCCYes Japan VCCI Compliance Yes KC Yes Yes **BSMI** CE Marking Compliance Yes **BNCI or BELUS** Yes CIT Yes GOST Yes Saudi Arabian Compliance Yes

(ICCP)

SABS Yes

43. Configurations of the HP EliteBook x360 830 G6 that are ENERGY STAR® certified are identified as HP EliteBook x360 830 G6 ENERGY STAR® on HP websites and on http://www.energystar.gov.

44. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.



Technical Specifications

ENVIRONMENTAL & INDUSTRY

nvironmental ata	Eco-Label Certifications & declarations	following approvals and r IT ECO declaratio US ENERGY STAR US Federal Energ EPEAT® 2019 Silv registration acco country. See http country. TCO Certified Edg China Energy Con	y Management Program (FE er registered in the United S rding to IEEE 1680.1-2018 E c://www.epeat.net for regis se servation Program (CECP) onmental Protection Admin	nore of these marks: MP) States. Based on EPEAT® EPEAT®. Status varies by tration status in your		
	System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".				
	Energy Consumption (in accordance with US					
	ENERGY STAR® test					
	method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
	Normal Operation	4.26	4.42	4.3		
	(Sort idle)					
	Normal Operation (Long idle)	2.66	2.77	2.69		
	Sleep	0.88	0.92	0.9		
	Off	0.36	0.37	0.36		
		offered within the model	ted is for an ENERGY STAR® family. HP computers mark t with the applicable U.S. En	ed with the ENERGY		
		Agency (EPA) ENERGY STA does not offer ENERGY ST efficiency data listed is fo	R® specifications for compu AR® compliant configuration or a typically configured PC ower supply, and a Microsoft	iters. If a model family ns, then energy featuring a hard disk		
	Heat Dissipation*	Agency (EPA) ENERGY STA does not offer ENERGY ST efficiency data listed is fo drive, a high efficiency po system.	.R® specifications for compu AR® compliant configuration or a typically configured PC (wer supply, and a Microsoft)	iters. If a model family ns, then energy featuring a hard disk t Windows® operating		
	Heat Dissipation*	Agency (EPA) ENERGY STA does not offer ENERGY ST efficiency data listed is fo drive, a high efficiency po system.	R® specifications for compu AR® compliant configuration or a typically configured PC to ower supply, and a Microsoft 230VAC, 50Hz	nters. If a model family ns, then energy featuring a hard disk t Windows® operating 100VAC, 60Hz		
	Heat Dissipation* Normal Operation (Short idle)	Agency (EPA) ENERGY STA does not offer ENERGY ST efficiency data listed is fo drive, a high efficiency po system.	.R® specifications for compu AR® compliant configuration or a typically configured PC (wer supply, and a Microsoft)	iters. If a model family ns, then energy featuring a hard disk t Windows® operating		
	Normal Operation	Agency (EPA) ENERGY STA does not offer ENERGY ST efficiency data listed is fo drive, a high efficiency po system.	R® specifications for compu AR® compliant configuration or a typically configured PC to ower supply, and a Microsoft 230VAC, 50Hz	uters. If a model family ns, then energy featuring a hard disk t Windows® operating 100VAC, 60Hz		
	Normal Operation (Short idle) Normal Operation	Agency (EPA) ENERGY STA does not offer ENERGY ST efficiency data listed is fo drive, a high efficiency po system. 115VAC, 60Hz 14	R® specifications for compu AR® compliant configuration or a typically configured PC is ower supply, and a Microsoft 230VAC, 50Hz 15	oters. If a model family ns, then energy featuring a hard disk t Windows® operating 100VAC, 60Hz 15		



the service level is attained for one hour.

Technical Specifications

Declared Noise Emissions	Sound Power Sound Press (L _{WAd} , bels) (L _{pAm} , decib				
(in accordance with ISO 7779 and ISO 9296)					
Typically Configured – Idle	2.5				
Fixed Disk – Random writes	2.6				
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: • 3 USB ports • 1 PC card slot (type I/II) • 1 ExpressCard/54 slot • 1 IEEE 1394 Port • 2 SODIMM memory slots • Optional expansion base docking station • 1 multi-bay II storage port • Interchangeable HDD Spare parts are available throughout the warranty period and or for up to "5"				
Batteries	years after the end of production. This battery(s) in this product comply with EU Directive 2006/66/EC				
	Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium				
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the Silver level, see http://www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per IS011469 and IS01043. This product contains 5.69% post-consumer recycled plastic (by wt.) This product is 96.4% recycle-able when properly disposed of at end of life. 				
Packaging Materials	External:	PAPER/Corrugated		264	
	Internal:	PLASTIC/EPE (Expande		47	



Technical Specifications

	PLASTIC/Polypropylene - PP	3
	PLASTIC/Polyethylene low density - LDPE	14
Material Usage	This product does not contain any of the following substances in excregulatory limits (refer to the HP General Specification for the Environment/supplyorspecifications.html):	onment at
	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP) Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface do be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and cretail packaging has been voluntarily removed from most applications. 	esigned to
	 Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (T 	ВТО)
Packaging Usage	HP follows these guidelines to decrease the environmental impact packaging: • Eliminate the use of heavy metals such as lead, chromium, nand cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in pa	mercury
	 materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials. Use readily recyclable packaging materials such as paper an corrugated materials. Reduce size and weight of packages to improve transportations. 	ials in
	efficiency. • Plastic packaging materials are marked according to ISO 114 DIN 6120 standards.	



Technical Specifications

= 1 6 116 11	
End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programming many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales of Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to protreatment information for each product type for use by treatment facil This information (product disassembly instructions) is posted on the Her Packard web site at: http://www.hp.com/go/recyclers . These instructions be used by recyclers and other WEEE treatment facilities as well as HP customers who integrate and re-sell HP equipment.
HP, Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.ht Eco-label certifications
	http://www8.hp.com/us/en/hp-
	information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=0 55842
	and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 13.3 inch diagonal FHD WLED BrightView UWVA 72 percent cg 400 nits eDP 1.4+PSR2 ultraslim

 Outline Dimensions (W x H x D)
 299.06 x 185.54 (max.)

 Active Area
 293.76 x 165.24

Weight 170 g max. (panel only)

Diagonal Size 13.3"
Thickness 2.0 mm

Interface eDP 1.4 w/ PSR2 (2 lane)



Technical Specifications

Surface Treatment BrightView Glass

Touch Enabled Yes

Contrast Ratio 1500:1 (typical)

Refresh Rate 60 Hz

Brightness 400 nits typ.

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB
Backlight WLED

Color Gamut Coverage 72% of NTSC

Color Depth 8 bit

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch diagonal FHD WLED Anti-glare UWVA 72 percent cg 400 nits eDP 1.4+PSR2 ultraslim Outline Dimensions (W x H x D) 299.06 x 185.54 (max.)
Active Area 293.76 x 165.24

Weight 170 q max. (panel only)

Diagonal Size 13.3"

Thickness 2.0 mm

Interface eDP 1.4 w/ PSR2 (2 lane)

Surface Treatment Anti-glare Glass

Touch Enabled Yes

Contrast Ratio 1500:1 (typical)

Refresh Rate 60 Hz

Brightness 400 nits typ.

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB
Backlight WLED

Color Gamut Coverage 72% of NTSC

Color Depth 8 bit

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch diagonal FHD WLED BrightView UWVA 45 percent cg 250 nits eDP slim Outline Dimensions (W x H x D) 300.56 x 187.77 max. (w/ PCB & w/o bracket)

 Active Area
 293.76 x 165.24 typ.

 Weight
 <260 max. (panel only)</td>

Diagonal Size 13.3"

Thickness 3.0 mm max.
Interface eDP 1.2 (2 lane)
Surface Treatment BrightView Glass

Touch Enabled Yes

Contrast Ratio 600:1 (typ)
Refresh Rate 60 Hz
Brightness 250 nit typ

Pixel Resolution 1920 x 1080 (FHD)



Technical Specifications

Format of LCD Pixel Arrangement RGB
Backlight WLED

Color Gamut Coverage 45% of NTSC

Color Depth 6 bit

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch diagonal FHD WLED BrightView UWVA 72 percent cg 1000 nits eDP 1.4+PSR2 flat Privacy

 Outline Dimensions (W x H x D)
 298.76 x 186.04 mm (typ.)

 Active Area
 293.76 x 165.24 mm (typ.)

Weight 255 g (max)
Diagonal Size 13.3 inch
Thickness 3.0 mm (max)
Interface eDP 1.4

Surface Treatment BrightView Glass

Touch Enabled YES

Contrast Ratio

Refresh Rate

Brightness*

2000:1(typ.)

60 Hz

1000 nits

Pixel Resolution 1920 x 1080(FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

Color Gamut Coverage 72% of NTSC

Color Depth 8 bit

Viewing Angle UWVA 85/85/85

*Touch-enabled display and Sure View privacy panel will lower actual brightness.

Panel LCD 13.3 inch diagonal FHD WLED Anti-Glare UWVA 72 percent cg 1000 nits eDP 1.4+PSR2 flat Privacy Outline Dimensions (W x H x D) 298.76 x 186.04 mm (typ.)

Active Area 293.76 x 165.24 mm (typ.)

Weight 255 g (max)
Diagonal Size 13.3 inch
Thickness 3.0 mm (max)
Interface eDP 1.4

Surface Treatment Anti-glare Glass

Touch Enabled YES

Contrast Ratio 2000:1 (typ.)

Refresh Rate 60 Hz
Brightness 1000 nits

Pixel Resolution 1920 x 1080(FHD)



Technical Specifications

Format of LCD Pixel Arrangement RGB Backlight LED

Color Gamut Coverage 72% of NTSC

Color Depth 8 bit

Viewing Angle UWVA 85/85/85

STORAGE AND DRIVES

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 128 GB 2280 M2 SATA-3 TLC Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface ATA-8, SATA 3.0
Maximum Sequential Read Up To 520 MB/s
Maximum Sequential Write Up To 450 MB/s
Logical Blocks 250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP

SSD 256 GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up To 3167 MB/s
Maximum Sequential Write Up To 1663 MB/s
Logical Blocks 500.118.192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2



^{*}Touch-enabled display and Sure View privacy panel will lower actual brightness.

Technical Specifications

SSD 256 GB 2280 M2 SATA-3 Self Encrypted OPAL2 TLC Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface ATA-8, SATA 3.0
Maximum Sequential Read Up To 530 MB/s
Maximum Sequential Write Up To 515 MB/s
Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP

256 GB 2280 PCIe NVMe Value Solid State Drive Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm)

Weight 0.02 lb (10 g)

Interface PCIe NVMe Gen3X4

Maximum Sequential Read Up To 1700 MB/s

Maximum Sequential Write Up To 600 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512 GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 512 GB
NAND Type MLC

Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm)

Interface PCIe NVMe Gen3X4

Maximum Sequential Read Up To 2600 MB/s

Maximum Sequential Write Up To 1400 MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512 GB 2280 M2 SATA- Form Factor
3 TLC FIPS Capacity

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC



Technical Specifications

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface ACS-3, SATA 3.2
Maximum Sequential Read Up To 530 MB/s
Maximum Sequential Write Up To 400 MB/s
Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP

SSD 512 GB 2280 PCIe-3x4 Form Factor NVMe Self Encrypted OPAL2 Capacity TLC

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm)

Weight 0.02 lb (10 g)

Interface PCIe NVMe Gen3X4

Maximum Sequential Read Up To 2900 MB/s

Maximum Sequential Write Up To 1400 MB/s

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 1 TB 2280 PCIe-3x4 NVMe TLC SS Form Factor M.2 2280
Capacity 1 TB
NAND Type TLC

Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm)

Interface PCIe NVMe Gen3X4

Maximum Sequential Read Up to 3480 MB/s

Maximum Sequential Write Up to 2800 MB/s

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 2 TB 2280 PCIe-3x4 NVMe TLC SS Form Factor M.2 2280
Capacity 2 TB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up to 3000 MB/s



Technical Specifications

Maximum Sequential Write

Logical Blocks

Operating Temperature

Features

Up to 2100 MB/s 3,907,029,168

32° to 158°F (0° to 70°C) [ambient temp]

TRIM; L1.2

SSD 512 GB 2280 PCIe

NVMe Value

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up to 1700 MB/s
Maximum Sequential Write Up to 1500 MB/s
Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512 GB PCIe NVMe + 32 GB Optane Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up to 2400 MB/s
Maximum Sequential Write Up to 1300 MB/s
Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2



Technical Specifications

NETWORKING/COMMUNICATIONS

802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 5.0 Combo¹, vPro™10,14

Intel® Wireless-AC 9560 Wireless LAN Standards

IEEE 802.11a IEEE 802.11b IEEE 802.11g

IEEE 802.11n IEEE 802.11ac Wi-Fi® certified

Interoperability Frequency Band

• 802.11b/q/n 2.402 - 2.482 GHz

• 802.11a/n

4.9 - 4.95 GHz (Japan)

5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCSO ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³

•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/q mode

AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification •IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

•WAPI

Network Architecture

Ad-hoc (Peer to Peer) Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² 802.11b: +18.5dBm minimum

• 802.11q: +17.5dBm minimum • 802.11a: +18.5dBm minimum

 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum

Power Consumption

Transmit mode 2.0 W

Receive mode 1.6 W

•Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated)



Technical Specifications

Connected Standby 10mW

•Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity ³ **802.11b, 1Mbps: -93.5dBm maximum**

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications

Form Factor PCI-Express M.2 MiniCard

Dimensions **Type 2230: 2.3 x 22.0 x 30.0 mm**

Weight Type 2230: 2.8g
Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON

- Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/q (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2 Compliant
Frequency Band 2402 to 2480 MHz
Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate¹ 2.17 Mbps

BLE: 1 Mbps signaling data rate¹ 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device

with a maximum transmit power of + 4 dBm for BR and EDR.



Technical Specifications

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Electrical Interface

USB 2.0 compliant

Bluetooth Software

Microsoft Windows Bluetooth Software

Supported Link Topology

Power Management Certifications Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C. Section 15.247 & 15.249

Power Management Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL. CSA. and CE Mark

Bluetooth Profiles

BT4.1-ESR 5/6/7 Compliance

Supported LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 – Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

10. Sold separately or as an optional feature.

14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

Intel® Wireless-AC 9560 802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 5.0 Combo¹, non-vPro™¹0,14

Wireless LAN Standards IEEE 802.11a

IEEE 802.11b IEEE 802.11g

IEEE 802.11n

IEEE 802.11ac

Interoperability Wi-Fi® certified
Frequency Band • 802.11b/g/n

2.402 - 2.482 GHz

• 802.11a/n

4.9 - 4.95 GHz (Japan)

5.15 - 5.25 GHz 5.25 - 5.35 GHz

5.47 - 5.725 GHz



Technical Specifications

5.825 - 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³ • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode

only

AES-CCMP: 128 bit in hardware

• 802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

• IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

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• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

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 802.11n HT40(2.4GHz): +14.5dBm minimum
 802.11n HT20(5GHz): +15.5dBm minimum
 802.11n HT40(5GHz): +14.5dBm minimum
 802.11ac VHT80(5GHz): +11.5dBm minimum
 802.11ac VHT160(5GHz): +11.5dBm minimum

Power Consumption • Trans

Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
 Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW
 Radio disabled 8 mW

Power Management ACPI and PCI Express

ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity ³ **802.11b, 1Mbps: -93.5dBm maximum**

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card



Technical Specifications

to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm

Weight Type 2230: 2.8q Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

> Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

0 to 50,000 ft (15,240 m) Non-operating

LED Activity LED Amber – Radio OFF; LED White – Radio ON

Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH) Channels BLE: 0~39 (2 MHz/CH)

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BLE: 1 Mbps signaling data rate 0.2 Mbps

1. Actual throughput may vary.

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channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

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with a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software

Supported Link Topology

Microsoft Windows Bluetooth Software

Microsoft Windows ACPI, and USB Bus Support Power Management Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

BT4.1-ESR 5/6/7 Compliance

Supported

LE Link Layer Ping LE Dual Mode

LE Link Layer



Technical Specifications

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

10. Sold separately or as an optional feature.

14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

Intel® Wi-Fi 6 AX200
802.11a/b/g/n/ac/ax
(2 x 2) and Bluetooth® 5.0
Combo¹, vPro™¹0,18

Wireless LAN Standards IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11h

IEEE 802.11k IEEE 802.11r IEEE 802.11v Wi-Fi® certified

Interoperability Frequency Band

• 802.11b/g/n/ax 2.402 – 2.482 GHz • 802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz

5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz

Data Rates
• 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³ • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode

only



Technical Specifications

AES-CCMP: 128 bit in hardware

802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

• IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

• WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Roamina IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +18.5dBm minimum

• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum

 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum

802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption Transmit mode 2.0 W

Receive mode 1.6 W

 Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated)

 Connected Standby 10mW Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b. 1Mbps: -93.5dBm maximum

• 802.11b, 11Mbps: -84dBm maximum • 802.11a/q, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n. MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum

• 802.11ac, MCS9: -59dBm maximum • 802.11ax, MCS11(HT40): -59dBm maximum • 802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3q

Operating voltage 3.3v +/- 9%

Temperature Operating: 14° to 158° F (-10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)



Technical Specifications

Humidity Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 95% (non-condensing)

Altitude Operating: 0 to 10,000 ft (3,048 m)

Non-operating: 0 to 50,000 ft (15,240 m)

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available

Channels

Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate¹ 2.17 Mbps

BLE: 1 Mbps signaling data rate¹ 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device

with a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software

Supported Link Topology

Microsoft Windows Bluetooth Software

Power Management

Power Management

Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)



Technical Specifications

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

10. Sold separately or as an optional feature.

18. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

Intel® Wi-Fi 6 AX200 802.11a/b/g/n/ac/ax (2 x 2) Bluetooth® 5 Combo¹, non-vPro™¹0.18 Wireless LAN Standards

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11d
IEEE 802.11h
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r

IEEE 802.11v

Wi-Fi certified

Interoperability
Frequency Band

• 802.11b/g/n/ax 2.402 – 2.482 GHz • 802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³ • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode

only

• AES-CCMP: 128 bit in hardware

• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

• WPA2 certification

• IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

• WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)
Infrastructure (Access Point Required)



Technical Specifications

Roaming IEEE 802.11 compliant roaming between access points

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802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum

802.11ax HT40(2.4GHz): +10dBm minimum
 802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW WLAN Associated)
 Idle mode 50 mW WLAN unassociated)

Connected Standby 10mW
 Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ •802.11b, 1Mbps: -93.5dBm maximum

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• 802.11a/g, 6Mbps: -86dBm maximum
• 802.11a/g, 54Mbps: -72dBm maximum
• 802.11n, MCS07: -67dBm maximum
• 802.11n, MCS15: -64dBm maximum
• 802.11ac, MCS0: -84dBm maximum
• 802.11ac, MCS9: -59dBm maximum

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Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz



Technical Specifications

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Channels

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Signaling Data Rate

Legacy: 3 Mbps signaling data rate¹ 2.17 Mbps BLE: 1 Mbps signaling data rate¹ 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device

with a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software

Supported Link Topology **Microsoft Windows Bluetooth Software**

Power Management

Microsoft Windows ACPI, and USB Bus Support

Certifications

FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles
Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode

LE Link Layer
LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

10. Sold separately or as an optional feature.

18. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other



Technical Specifications

802.11ax devices.

Intel® XMM™ 7360 LTE-Advanced Cat 915

Technology/Operating

FDD LTE: 2100 (Band 1). 1900 (Band 2). 1800 (Band 3).

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300

(Band 30), 1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol

standards

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up

to 450Mbps: UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone. A-GPS (MS-A. MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098

MHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

> DC-HSPA+: 42 Mbps (Download). 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

LTE: 23 dBm Maximum output power

HSPA+: 23.5 dBm

LTE: 1,200 mA (peak); 900 mA (average) Maximum power HSPA+: 1,100 mA (peak); 800 mA (average) consumption

Form Factor M.2, 3042-S3 Key B

Weiaht 5.8 q

Dimensions 42 x 30 x 2.3 mm

(Length x Width x

Thickness)

15. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

Intel® XMM™ 7262 LTE-Advanced Cat 615

Technology/Operating

FDD LTE: 2100 (Band 1), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900

(Band 8), 800 (Band 20), 700 (Band 28),

HSPA+: 2100 (Band 1), 850 (Band 5), 900 (Band 8)

Wireless protocol

bands

3GPP Release 11 LTE Specification CAT.6, DL 40MHz BW throughput up to 300Mbps; UL 20MHz throughput up to 50Mbps standards

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B and XTRA)

GPS bands 1575.42 MHz ± 1.023 MHz. GLONASS 1596-1607MHz

LTE: 300 Mbps (Download), 50 Mbps (Upload) Maximum data rates

> DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) UMT: 384 kbps (Download), 384 kbps (Upload)

LTE: 23 dBm Maximum output power



Technical Specifications

HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

Dimensions (Length x Width x Thickness) 42 x 30 x 2.3 mm

15. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

Intel® XMM™ 7560 LTE-Advanced Pro Cat 16¹⁷ Technology/Operating

bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700

(Band 12 lower),

700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower), 850

(Band 18 lower),

850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700

(Rand 28).

700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band

41), 3500 (Band 42), 5200 (Band 46 RX only)

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MH

Wireless protocol standards

3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW throughput up to 978Mbps; UL-CAT.13 40MHz throughput up to

150Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-B and LTO)

GPS Bands GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou

1561.098 ± 2.046 MHz

Maximum data rates LTE: 978 Mbps (Download), 150 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm in all bands except B41

LTE B41 HPUE: 26dBm HSPA+: 23.5 dBm

Maximum power LTE: 1,200 mA (peak); 900 mA (average) consumption HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight **6 g**

Dimensions **42 x 30 x 2.3 mm**

(Length x Width x Thickness)



Technical Specifications

17. Gigabit class Category 16 4G LTE module is optional and must be configured at the factory. Module designed for up to 1 Gbps download speeds as carriers deploy 5 carrier aggregation and 100Mhz channel bandwidth, requires activation and separately purchased service contract. Backwards compatible to HSPA 3G technologies. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

NXP NPC300 Near Field Communication Module

Dimensions (L x W x H) Module 17 mm by 10 mm by 2.0 mm

Chipset NPC300
System interface 12C

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD) Mode¹ ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation (PICC-

VICC) Mode1

ISO/IEC 14443 A

ISO/IEC 14443 B and B'

MIFARE FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer Raw RF Data Rates 106, 212, 424, 848 kbps

Operating temperature -25 C to 80°C
Storage temperature -20°C to 125°C
Humidity 10-90% operating

5-95% non-operating

Supply Operating voltage 2.7 to 5.5 Volts I/O Voltage 1.8V or 3.3V

10. Sold separately or as an optional feature.

Power Consumption (Booster enable, VBAT= 3.3V, VCC_BOOST = 5V) Polling 710.93 mW

Detected Test Tag Type 1 152.09 mW

Detected Test Tag Type 2 341.26 mW

Detected Test Tag Type 3 383.76 mW



Technical Specifications

Detected Test Tag Type 4 312.26 mW

Antenna Antenna connector, O.3mm pitch, 7 connector FPC. Antenna matching

is external to module.

POWER

HP 65W Dimensions (H x W x D) 107.0 x 47.0 x 30.0mm

Smart AC adapter Weight **250g +/- 10g**

Input Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output Output power 65W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <11.0A

Connector 4.5mm Barrel Type

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude **0 to 16,400 ft (0 to 5000m)**

Humidity 20% to 95% Storage Humidity 10% to 95%

EMI and Safety CE Mark - full compliance with LVD and EMC directives
Certifications Worldwide cafety standards - IECGORGO ENGORGO III.6

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.

HP 45W Dimensions (H x W x D) 3.74 x 1.57 x 1.04 in (9.5 x 4.0 x 2.65 cm)

Smart AC adapter Weight **0.386 lb (175g) max**

Input 90 to 265 VAC

Input Efficiency 87.74% at 115Vac and 88.4% at 230Vac

Input frequency range 47 to 63 Hz
Input AC current 1.4 A at 90 VAC

Output Output power **45W**

DC output 19.5V

Hold-up time 5 msec at 115 VAC input

Output current limit <8.0A



Technical Specifications

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable

cords

Environmental Design Operating 32° to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4° to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% Storage Humidity 10% to 95%

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W EM Smart AC adapter Dimensions $(H \times W \times D)$

102 x 55 x 30mm

Weight 270g +/- 10g

Input Input Efficiency 87% min at 115V/230V

Input frequency range 47 to 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

Output DC output 65W(19.5V/3.33A)

Hold-up time 5 msec at 115 VAC input

Output current limit <11A, Over voltage protection- 29V max

automatic shutdown

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable

cords

Environmental Design Operating 0° to 35° C

temperature

Non-operating (storage) -20° to 85° C

temperature

Altitude 0 to 5,000 m
Humidity 0% to 95%
Storage Humidity 0% to 95%

EMI and Safety Certifications CE Mark - EMC directives; Worldwide safety standards

-IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-

US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE; Reliability - failure rate of less than 0.1% annually

within the first three years of operation.



Technical Specifications

AC Adapter 45 Watt nPFC USB tvpe C™

Dimensions $(H \times W \times D)$

Weight

Input

Output

62.0 x 62.0 x 28.5 mm

unit: 220g +/- 10g

Input Efficiency

Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec:5V

> : 81.5%9V: 86.7%10V: 87.5%12V: 87.8%15V:87.8%20V:87.8%

Input frequency range 47 ~ 63Hz

Input AC current

Max. 1.4 A at 90 Vac 5V/15W

Output Power

9V/27W 10V/37.5W 12V/45W 15V/45W 20V/45W

DC output 5V / 9V / 10V /12V / 15V / 20V

Hold-up time 5ms at 115 Vac input

Output current limit <5.0A

Connector

Environmental Design

USB Tvpe-C™ **Operating**

temperature

32°F to 95°F (0° to 35°C)

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

AC Adapter 65 Watt nPFC USB type C ™

Dimensions (H x W x D)

Weight

74 x 74 x 28.5 mm unit: 245g +/- 10g

Input Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 ~ 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

Output Power Output 65W

> DC output 5V/9V/10V/12V/15V/20V Hold-up time 5ms at 115 Vac input

Output current limit <8.0A



Technical Specifications

Connector Duck head / duck head power cord, without Smart ID DC connector

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% Storage Humidity 5% to 95%

EMI and Safety CE Mark - full compliance with LVD and EMC directives

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FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 100,000 hours at 25°C ambient condition.

HP 4 Cell WHr 53 Long Life -PL Fast Charge Dimensions (H x W x D)

5.58 mm * 80.62 mm * 269.2 mm

Weight

_

Cells/Type

3-cell; Polymer

243q

Energy

Voltage 7.7V

Amp-hour capacity 6.9Ah

Watt-hour capacity
Operating (Charging)

53.2Wh 0°C ~ 45°C

Temperature

0----tin-(Di-ab---in-) 440+-

Optional Travel Battery

Operating (Discharging) 14° to 122°F (-10° to 60°C)

Available

y

Country of Origin

China



Options and Accessories (Sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Basic Backpack	H1D24AA
	HP Slim Top Load	F3W15AA
Docking	HP Thunderbolt Dock 120W G2	2UK37AA
	HP Thunderbolt Dock 120W G2 TAA	2UK37AA
	HP Elite 90W Thunderbolt 3 Dock	1DT93AA
	HP USB-C Dock G4	3FF69AA
	HP USB-C Mini Dock	1PM64AA
	HP USB-C Travel Dock	TOK29AA
	HP USB Travel Dock	TOK30AA
	HP USB-C Universal Dock	1MK33AA
	HP Adjustable Dual Display Stand	AW664AA
Input/Output	HP Slim Wireless Keyboard and Mouse	T6L04AA
mpat, vatpat	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U2OAA
	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Conferencing Keyboard	K8P74AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP Wireless Collaboration Keyboard	Z9N39AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Slim Bluetooth Mouse to AMO	F3J92AA
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP Essential USB Mouse	2TX37AA
	HP Elite Presenter Mouse	2CE30AA
	HP USB-C to USB 3.0 Adapter	N2Z63AAA
	HP USB-C to USB-A Hub	Z6A00AA
	HP USB-C to HDMI 2.0	1WC36AA
	HP USB-C to VGA	N9K76AA
	HP HDMI to DVI	F5A28AA
	HP USB-C to RJ45	V7W66AA
	HP USB to RJ45	N7P47AA
	HP HDMI to VGA	H4F02AA
Power	HP 65W Slim AC Adapter	H6Y82AA
	HP 90W Slim AC Adapter	Н6Ү8ЗАА



Options and Accessories (Sold separately and availability may vary by country)

	HP 90W Slim Combo AC Adapter w/ USB	H6Y84AA
	HP 45W Smart AC Adapter	H6Y88AA
	HP 65W Smart AC Adapter	Н6Ү89АА
	HP 90W Smart AC Adapter	Н6Ү9ОАА
	HP 45W 2-prong 4.5 mm DC jack AC Adapter	L6F60AA
	HP 45W USB-C Power Adapter	1HEO7AA
	HP 65W USB-C Power Adapter	1HE08AA
	65W USB-C Slim Power Adapter	3PN48AA
	HP Notebook Power Bank	N9F71AA
	HP USB-C Notebook Power Bank	1TZ86AA
UCC	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
	HP UC Wireless Mono Headset	W3K08AA
	HP UC Wireless Duo Headset	W3K09AA
Storage	HP USB External DVDRW Drive	F2B56AA
	HP 256GB M2 PCIe NVME SSD TLC (2280)	1FU87AA
	HP 512GB M2 PCIe NVME SSD TLC 2280)	1FU88AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Dual-Head Keyed Cable Lock	1AJ41AA
Other	HP TB Dock Audio Module	3AQ21AA
	HP Thunderbolt 120W 1m cable	3AQ23AA
	HP Thunderbolt 1m combo cable	3A25AA
	HP Rechargeable Active Pen	4KL69AA
Displays	HP EliteDisplay E243d 23.8-inch Docking Monitor	1TJ76AA
	HP EliteDisplay E243 23.8-inch Monitor	1FH47AA
	HP EliteDisplay E273q 27-inch Monitor	1FH52AA



Change Log

Date of change:	Version History:		Description of change:
June 10, 2019	From V1 to V2	Added	HP Cloud Recovery
June 20, 2019	From V2 to V3	Added	Environmental tab
July 2, 2019	From V3 to V4	Updated	Color Gamut
September 9, 2019	From V4 to V5	Updated	Intel® Optane™ and disclaimer for 1000 nit Sure View panel
November 6, 2019	From V5 to V6	Updated	Processors section
January 21, 2020	From V6 to V7	Added	Modern Connected Standby
May 27, 2020	From V7 to V8	Updated	Ports section

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